



Sample thickness determination by low-energy scanning transmission electron microscopy

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Motivation

- Scanning transmission electron microscopy (STEM) in high-angle annular dark-field mode (HAADF)

 ⇒ strong material (Z-) contrast
- Energies ≤ 30 keV ⇒ negligible knock-on damage
- Important parameter in analytical electron microscopy sample thickness
- Contrast depending on sample thickness and composition ⇒ determination of
- local sample thickness if composition is known [1]

Instrumentation

- Combined focused ion-beam (FIB)/SEM: FEI Strata 400S
 Annular semiconductor STEM-detector with bright-field (BF), dark-field (DF) and six azimuthal HAADF segments
- HAADF scattering angle range: 0.2-0.7 rad



Imaging Conditions

- Measurement of normalized image intensities
- Reference intensities for normalization from detector STEM images
- Inner part of HAADF segment visible at lowest magnification Brightness & contrast tuned to avoid over- and undersaturation and kept constant for sample imaging

$$I_{HAADF} = rac{I_S - I_B}{I_W - I_B}$$

I_{HAADF}: normalized image intensity $I_{\rm s}$: measured image intensity I_w : intensity of incident beam (white-level) I_B: offset intensity (black-level)



Monte-Carlo Simulations

- Use of NISTMonte package [2]
 Consideration of screened Rutherford (SRCS) and Mott (MCS) scattering crosssections
- Normalization for comparison with measured intensities
- Corrections for detector-related effects concerning collection current [3] and
- geometry [4] HAADF intensity by integration of scattering angle histogram



Initial Thickness Measurements In case of film sample via Dektak profilometer

- In case of wedge-shaped lamellas prepared by FIB milling via top-view SE SEM imaging
- Measurement of thickness offset at the edge t₀ and wedge angle α

Results: FHBC films

- Five films of fluorenyl hexa-peri-hexabenzocoronene (C100H98) with different nominal thickness (Z=3.5, p=1.1 g/cm³)
- Measurements at discrete multiples of nominal film thickness due to folding
- Correlation with nominal thickness and comparison with simulations
- Agreement with simulations based on SRCS
- Deviations for one film explaned by uncertainty of nominal thickness
- Improved agreement for shift of -20nm for nominal thickness (arrows)



Results: GaN- and W-lamellas

GaN- and W-lamellas with FIB-prepared wedges for a defined thickness profile $(\overline{Z}$ =19, ρ =6.1 g/cm³ and Z=74, ρ =19.3 g/cm³)

 $t = t_0 + x \cdot \tan \alpha$

- Intensity measurement along line with increasing thickness due to wedge shape
- Transformation of position coordinate x of linescan to sample thickness t via:
- Fit to simulated curve by adjusting t₀ and α
- Agreement with simulations based on MCS
- Agreement of fit parameters with measurements in top-view SE SEM images



Summarv

- Low-kV HAADF STEM intensity measurements enable local sample thickness determination by comparison with Monte-Carlo simulations
- Adequate adjustment of brightness and contrast necessary
- Normalization of measured intensities with intensity of the incident beam
- Consideration of detector-related effects during evaluation of simulations
- Materials with Z<6 described by screened Rutherford cross-sections, materials
- with Z>14 described by Mott cross-sections Results avaiable for FHBC (Z=3.5), GaN (Z=19) and W (Z=74), as well as C (Z=6) and Si (Z=14) [1]
- Initial thickness measurements by profilometer and top-view SE SEM imaging

References and Acknowledgement

- [1] T. Volkenandt et al. (2013), Microsc Microanal, submitted
- [2] N. Ritchie (2005), Surf Interface Anal 37, p. 1006
- [3] L. Reimer (1998), Heidelberg: Springer-Verlag [4] T. Volkenandt et al. (2010), Microsc Microanal **16**, p. 604
- [5] This work is funded by the Deutsche Forschungsgemeinschaft (DFG)